BMT352

3.0-4.0 GHz 1.5W High Linearity 5V 2-Stage Power Amplifier

Package Outline Dimension

### Top View

### Bottom View

### Side View

#### Notes:
2. Controlling dimensions: millimeter. Converted inch dimension are not necessarily exact.
3. Dimension b applies to metallized terminal and is measured between 0.15 and 0.30 mm from terminal tip.
4. Insulation thickness, clearance of overlap are user defined.
5. Insulation not completely shown for reasons of clarity.
BMT352
3.0-4.0 GHz 1.5W High Linearity 5V 2-Stage Power Amplifier

Suggested PCB Land Pattern and PAD Layout

• Notes
  1. Use 1 oz. copper minimum for top and bottom layer metal.
  2. A heatsink underneath the area of the PCB for the mounted device is required for proper thermal operation.
  3. Ground / thermal vias are critical for the proper performance of this device.

Package Marking

BMT352
YYWWXX

YY = Year, WW = Working Week,
XX = Wafer No.